

## ABSTRACT

While a vicinity of a bottom surface-side region of a pressure-sensitive adhesive sheet (3) corresponding to an adhesion region (R1) of a semiconductor chip (1) are sucked and held, a plurality of protruding portions (30) of a removing member (21) are brought into contact with the bottom surface of the semiconductor chip through the adhesive sheet at the region. Also, the adhesive sheet is sucked in between the respective protruding portions so as to change a surface bonding of the semiconductor chip to the adhesive sheet by adhesion to a point bonding, and further the removing member is moved along the bottom surface of the semiconductor chip so as to change a position of the point bonding and decrease bonding force to the adhesive sheet by the adhesion. Then, the semiconductor chip is removed from the adhesive sheet.